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Shallow Amorphizing Implant For Gettering Of Deep Secondary End Of Range 1 2 **Defects** 3 Abstract A pocket implant process to reduce defects. We provide a gate 4 5 structure, on a semiconductor substrate doped with a first conductivity type dopant. We 6 perform a pocket amorphizing implantation procedure to form a pocket implant region adjacent to the gate structure, and an amorphous pocket region. Next, we perform a 7 8 shallow amorphizing implant to form an amorphous shallow implant region. The 9 amorphous shallow implant region being formed at a second depth above the amorphous 10 pocket region. The substrate above the amorphous shallow implant region preferably remains crystalline. We perform a S/D implant procedure to form Deep S/D regions. We 11 12 perform an anneal procedure preferably comprised of a first soak step and a second spike step to recrystalilze the amorphous shallow implant region and the amorphous pocket 13 14 region, The defects created by the pocket implant are reduced by the shallow amorphous 15 implant.